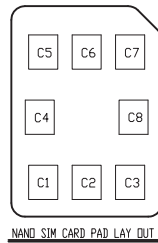
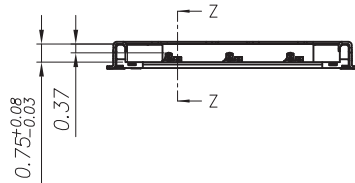
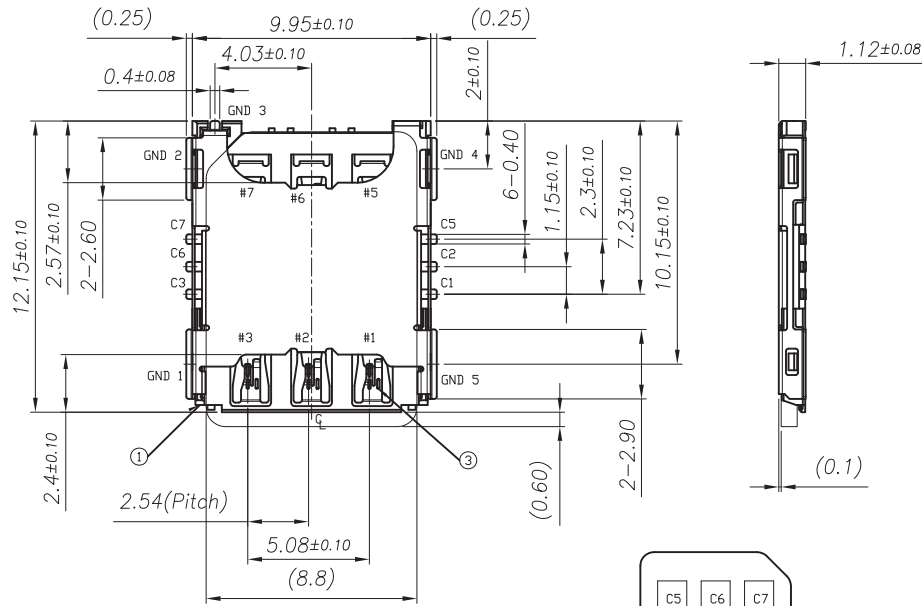
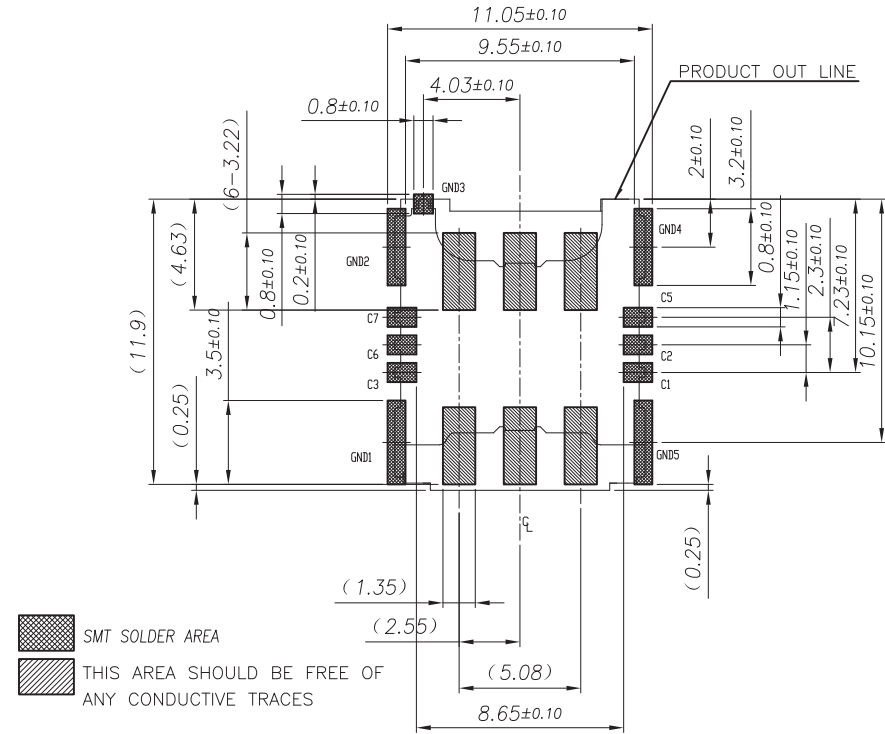


REV.	ECN NO OR DESCRIPTION	REVISED	DATE
▽	PROPOSE ONLY	ALLEN	2015.03.04



PIN NO.	NAME
C 1	VCC
C 2	RST
C 3	CLK
C 5	GND
C 6	VPP
C 7	I/O

NANO SIM CARD ASSIGNMENT



RECOMMENDED PCB LAYOUT TOP VIEW (TOLERANCE:±0.05)
RECOMMENDED METAL MASK T=0.12MM

- NOTES:
- MATERIAL:SEE TABLE
 - SPECIALITY:
 - Rated current: 0.5A Max
 - Rated voltage: 30V AC
 - Contact Resistance:100mohm MAX
 - Insulation Resistance:1000Mohm MIN 500V DC
 - Dielectric withstanding voltage: 500V AC/minute.
 - Solder ability:250±5 10±0.5s.
 - Durability:5000 Cycles
 - Mating and Unmating force
Insertion Force 10N Max
Withdrawal Force 0.5N Min

3. PART No.:

NS 0 DD - 11 00 06- 12 G

Nano SIM CON. G=gold flash
 0=WITHOUT POST 12=Product Order
 DD=WITH UPLOCK Pin NO. 6=6Pin
 11:HEIGHT 1.12mm 00=NORMAL TYPE.(ON PCB)

ITEM	DESCRIPTION	MATERIAL	FINISH	Q'TY
3	TERMINAL	COPPER ALLOY	GOLD PLATING ON CONTACT AREA SEE PLATING CODE NOTE; GOLD PLATING 0.05um ON SOLDER TAIL AREA; ALL OVER 2~4um NICKEL	6
2	SHELL	STAINLESS STEEL	GOLD PLATING 0.05um MIN ON SOLDER TAIL AREA ALL OVER 2~4um Ni . SUS301-H T=0.10mm	1
1	HOUSING	HIGH TEMP. THERMOPLASTIC	GLASS FILLED (OR EQUAL),UL 94V-0, BLACK,NO RECYCLED RESIN.	1

UNLESS OTHERWISE SPECIFIED TOLERANCES

Wellco T&C Co., Ltd

DECIMALS:	ANGLES:	TITLE	6Pin 1.12H PUSH PULL Nano SIM CARD CONN.		
X :±0.5	X :±2°	DWN	ALLEN	PART NO. NSODD-110006-12G	
X.X :±0.20	X.X :±1°	CHKD	KEVIN	SCALE:1:1	UNIT: mm
X.XX :±0.10		APVD	ERIC.W	SIZE: A3	SHEET:1OF 1

CUSTOMER COPY

